



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re application of: Koos et al.

Application No.: 10/690,084

Filed: October 20, 2003

Title: METHOD FOR FABRICATION OF
SEMICONDUCTOR INTERCONNECT
STRUCTURE WITH REDUCED
CAPACITANCE, LEAKAGE CURRENT, AND
IMPROVED BREAKDOWN VOLTAGE

Attorney Docket No.:
NOVLP068/NVLS-2818

Examiner: Vinh, Lan

Group: 1765

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first-class mail on December 1, 2005 in an envelope addressed to the Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.

Signed: _____

Leslie Russell
Leslie Russell

RESPONSE A

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

This is in response to the non-final Office Action mailed August 5, 2005.

Amendments to the Claims are reflected in the listing of claims which begin on page 2 of this papers.

Remarks/Arguments begin on page 10 of this paper.